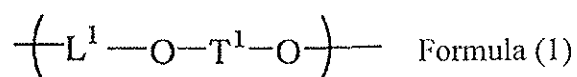


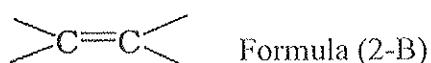
ADHESIVE COMPOSITION CONTAINING RESIN HAVING CARBON-CARBON MULTIPLE BOND

ABSTRACT

There is provided a highly heat-resistant adhesive composition that easily dissolves in various organic solvents, has excellent coating properties, and can form a thick-enough adhesive layer and that undergoes little thermogravimetric loss during high-temperature processes such as steps of metal bump bonding, CVD, and ion diffusion and achieves excellent bonding. An adhesive composition comprising a polymer that contains a unit structure of Formula (1):



- 10 (where L^1 is an arylene group or a combination of an arylene group and a sulfonyl group or a carbonyl group, and T^1 is a fluoroalkylene group, a cyclic alkylene group, an arylene group having a substituent, or a combination of an arylene group optionally having a substituent and a fluoroalkylene group or a cyclic alkylene group) and contains, at a terminal or in a side chain or the main chain, at least one group containing a structure of
- 15 Formula (2-A), a structure of Formula (2-B), or both structures:



NO SUITABLE FIG.